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**ASIP-Case Studies II(a):  
Heterogeneous Multicore Architecture for Image  
Sensor Processing featuring Tensilica Cores**

Tensilica Day 9.2.2016 @ IMS-Hannover

## DCT Company Profile

# Dream Chip Technologies ...



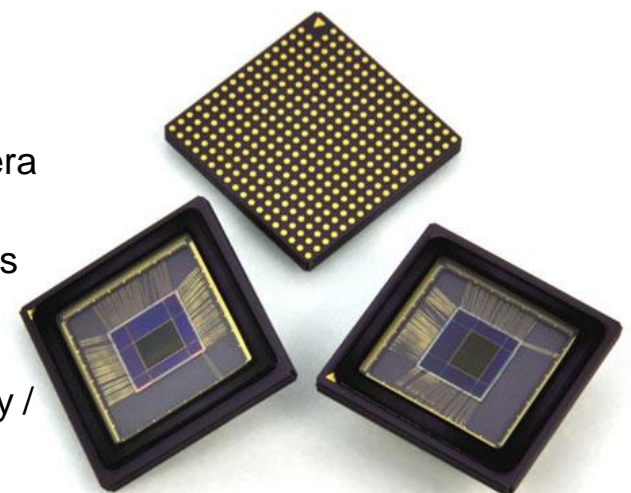
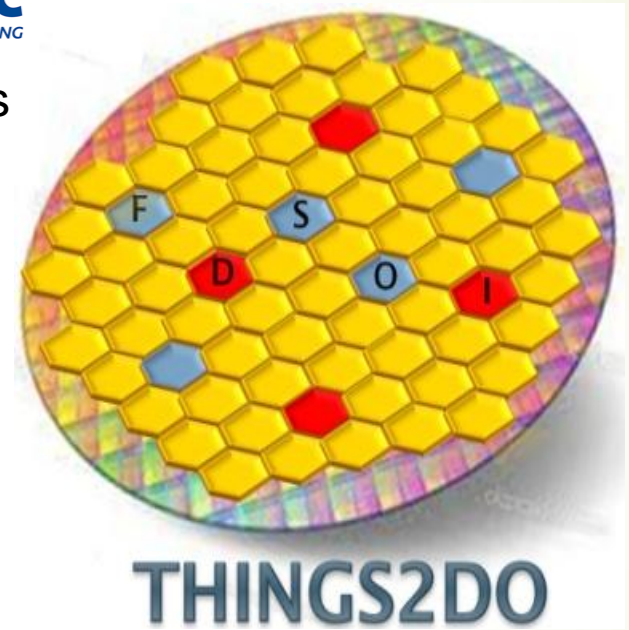
- Design Service Company especially for European customers in the SoC and embedded SW market.
    - Hardware and software solutions for real time imaging applications
    - Embedded software on various platforms
    - Concept engineering
  - **Cadence/Tensilica Design Center Partner since 2011**
  - **Tensilica Designs since 2005**
- 
- The **CODESIGN** Experts



# The Things2Do-Project



- Things2Do: THIN but Great Silicon 2 Design Objects
- Schedule: 1 April 2014 - 30 September 2018
- THINGS2DO is an ENIAC project addressing semiconductor energy efficiency and design & development ecosystems for FD-SOI-technology
- More than 50 companies, institutes and universities from 12 countries are addressing different applications for 22/28nm FDSOI technology
- The Dream Chip contribution
  - Part of **DreamChip** is to create a complex SoC design for camera based ADAS applications
  - Part of **LUH IMS** is the reference software on the heterogeneous SoC design from DCT
  - **CADENCE** supplies EDA tools and IP infrastructure to the project, **Global Foundries** supply the 22nm FD-SOI technology / manufacturing
  - Partners:



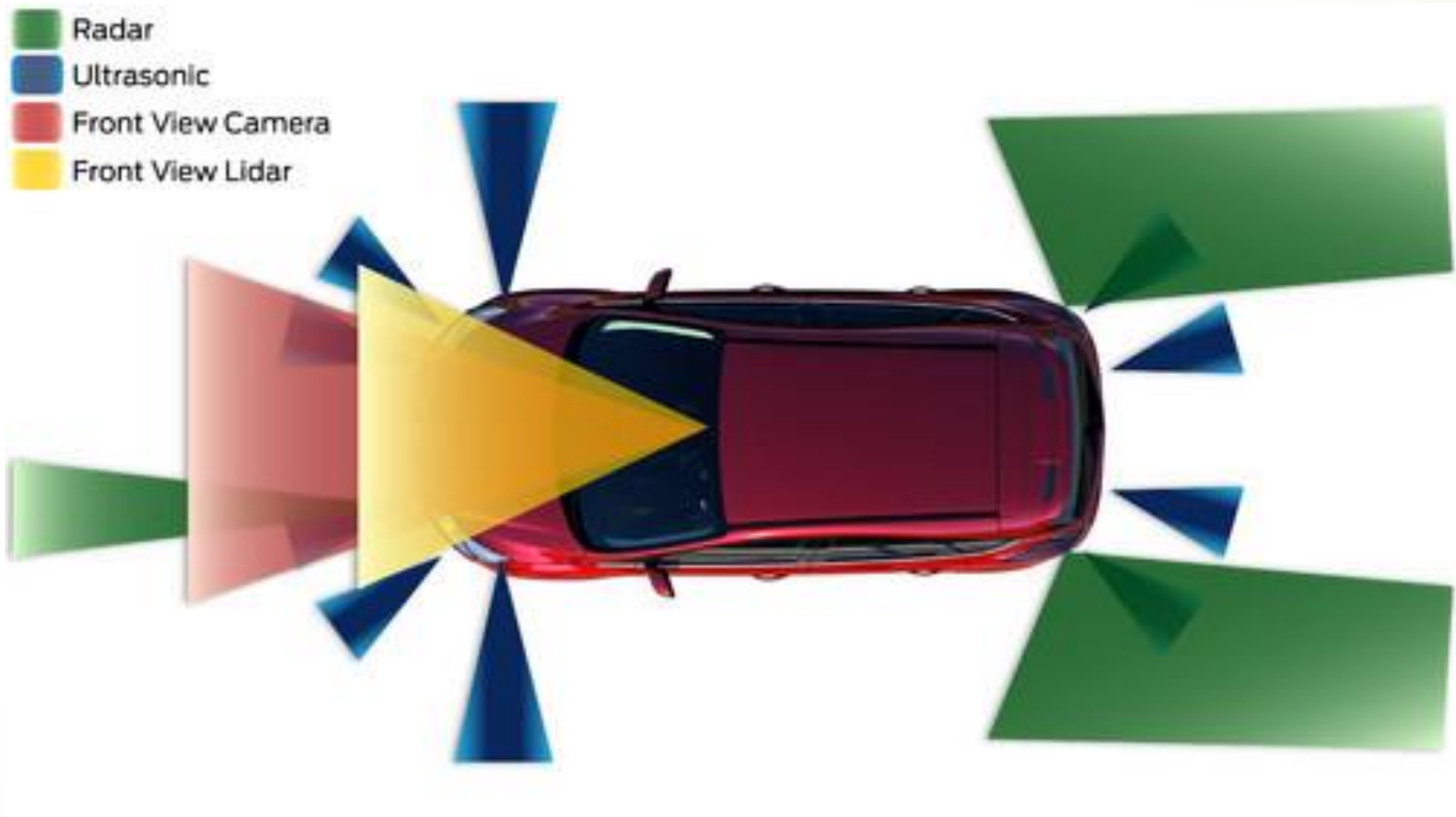
Audi  
Vorsprung durch Technik



# Advanced Driver Assistance Systems (ADAS) overview



## *Assisted Driving requires Cameras, Radar and Ultrasonic*

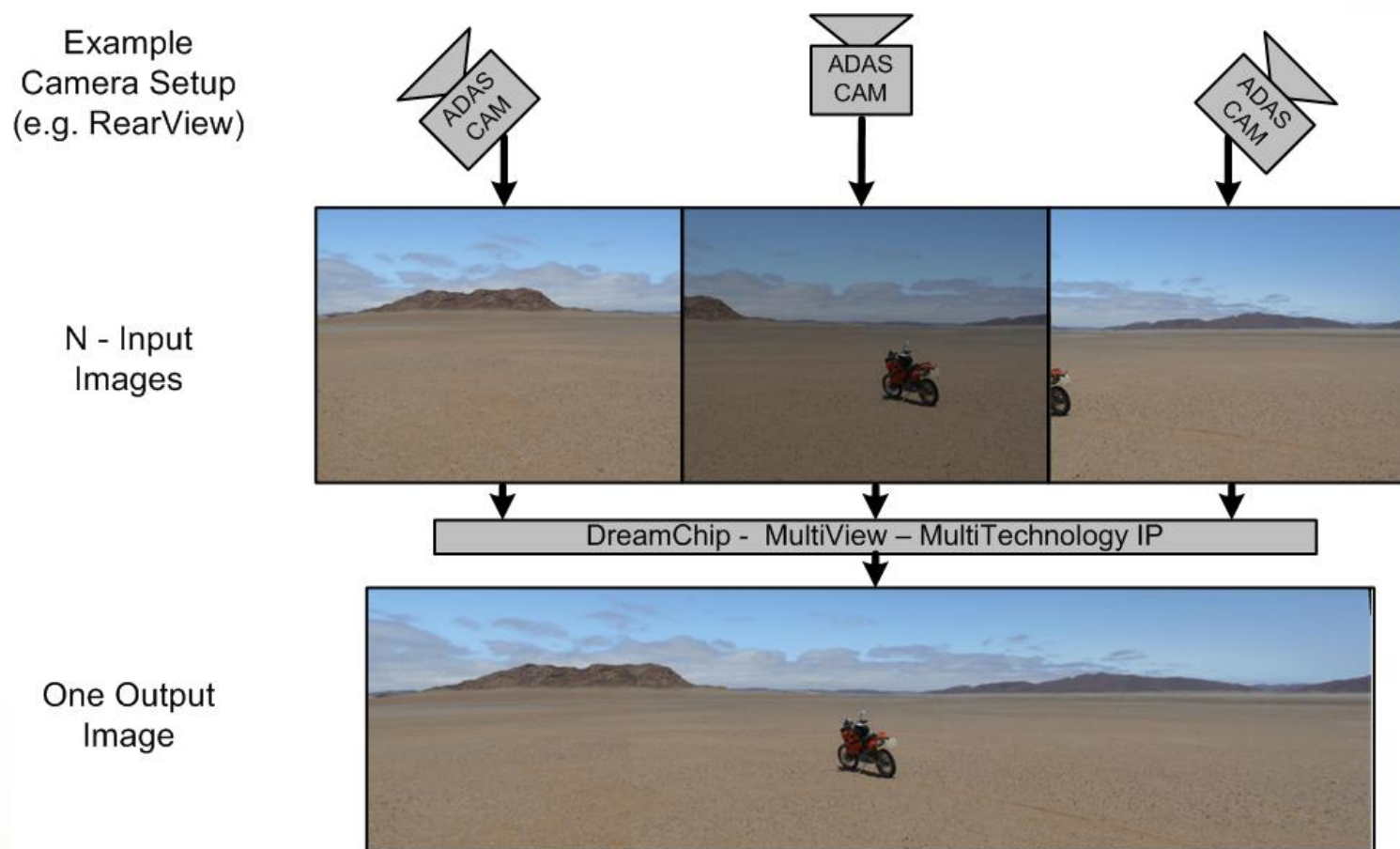


## Use Case #1: Digital Mirroring



## Use Case #1: Digital Mirroring - The Multiview Idea

- Automotive multi camera systems for Bird-View, Rear-View and Panorama-View are a major part of today's emerging technologies to make driving more safe and comfortable and to move towards autonomous vehicles.



## Use Case #2 : 360 deg Top View Camera



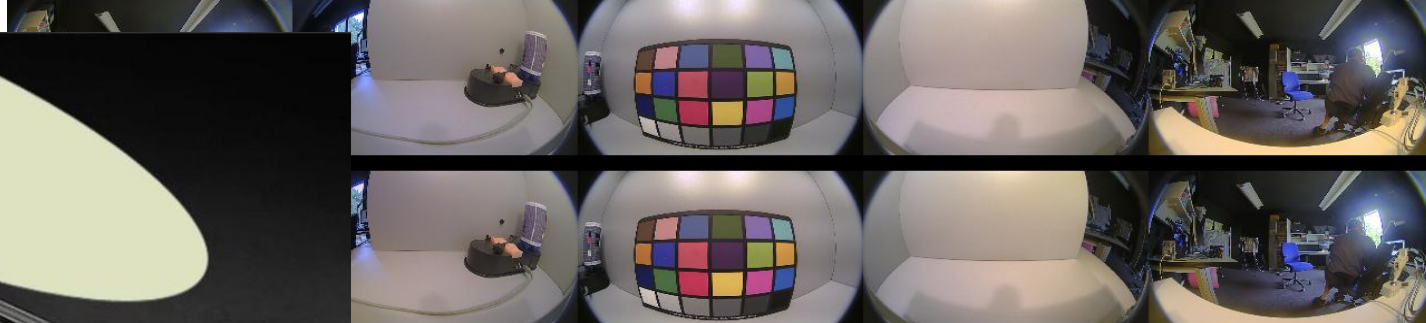


# TopView Harmonization

```

H   show help
Q   quit this program
X off harmonization bypass
F ON use filtered means
D off display measurement window positions
T ON use temporal low-pass filter for gains
W ON use difference-dependent weight for gains
B off force bottom gains to 1.0
C ON use smooth transition between edges
G off display gains on gray image
S   create screenshot
  
```

	avgR	avgG	avgB	avgR	avgG	avgB	avgR	avgG	avgB	avgR	avgG	avgB
upper left corner >>	134	170	204	160	157	165	184	172	167	109	106	88
upper right corner >>	149	142	132	153	152	157	78	78	82	98	111	144
lower left corner >>	126	124	135	121	118	120	189	174	181	191	168	136
lower right corner >>	145	140	140	137	135	137	153	143	133	209	180	122



R	gainG	gainR	weight	gainR	gainG	gainB	weight	gainR	gainG	gainB	weight	gainR	gainG	gainB	weight
5	0.806	0.848	1.000	0.966	0.951	0.895	1.000	0.911	0.940	0.971	1.000	0.846	0.860	1.013	1.000
5	1.052	1.117	1.000	1.097	1.064	1.030	1.000	1.182	1.163	0.987	1.000	1.170	1.240	1.198	1.000
8	1.205	0.951	1.000	1.092	1.087	1.073	1.000	0.853	0.883	0.873	1.000	0.895	0.924	0.988	1.000
6	0.920	0.927	1.000	1.173	1.133	1.146	1.000	1.117	1.082	1.042	1.000	0.776	0.830	1.052	1.000

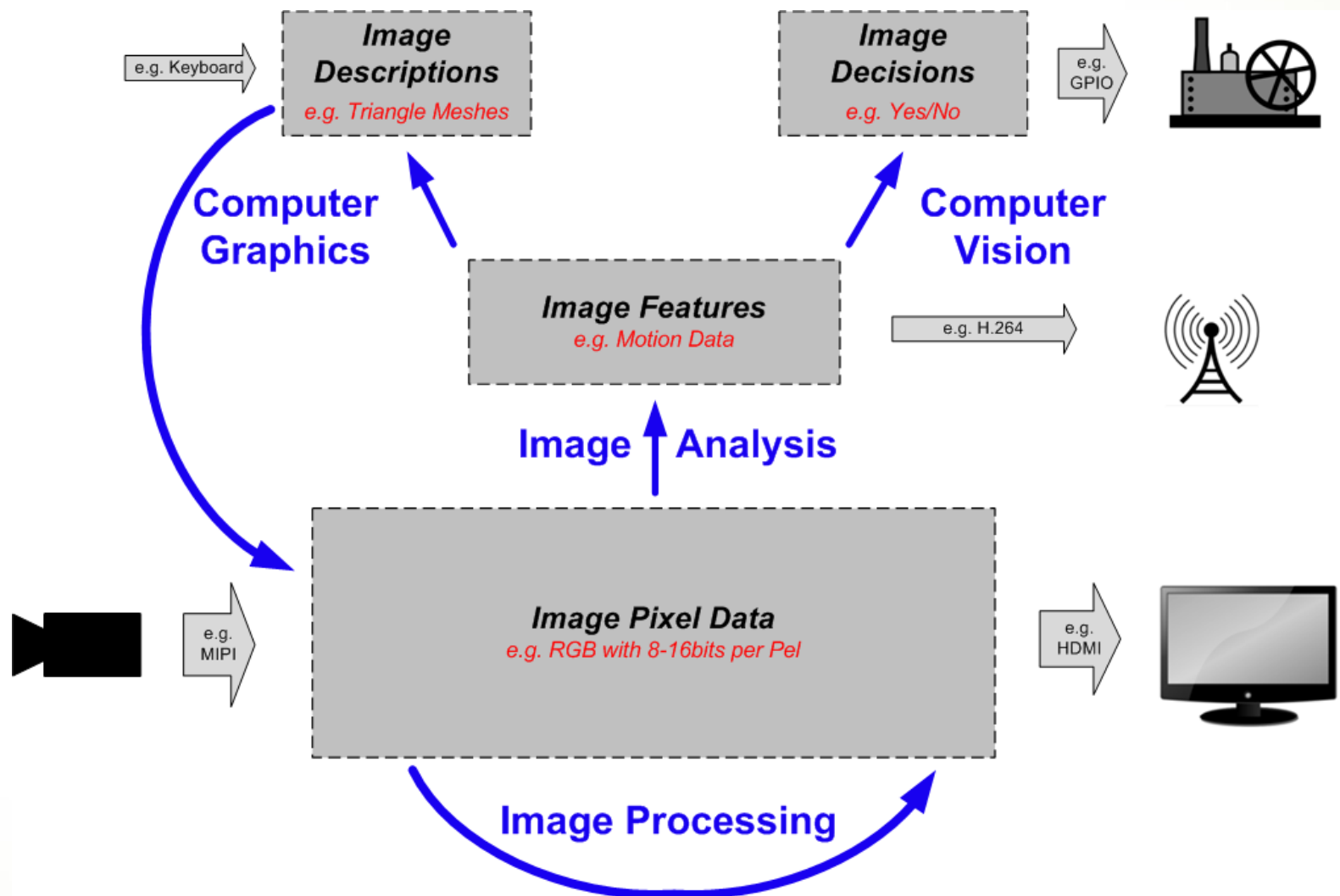


Verbaupositionen der Kameras

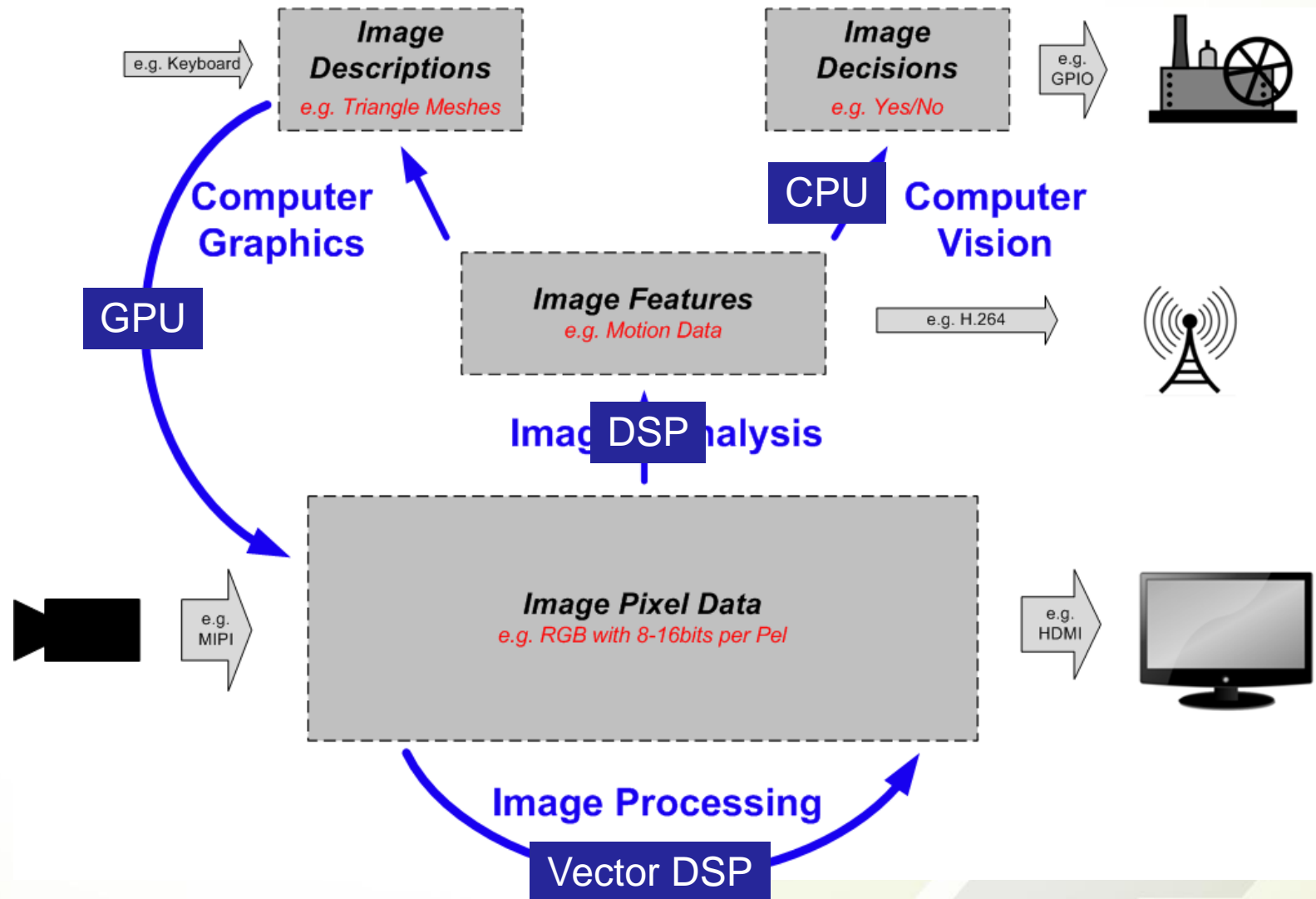
Erfassungsbereiche der Kameras

# *Introduction and Classification Image Sensor Processing (ISP)*

# Introduction – Image Sensor Processing Overview

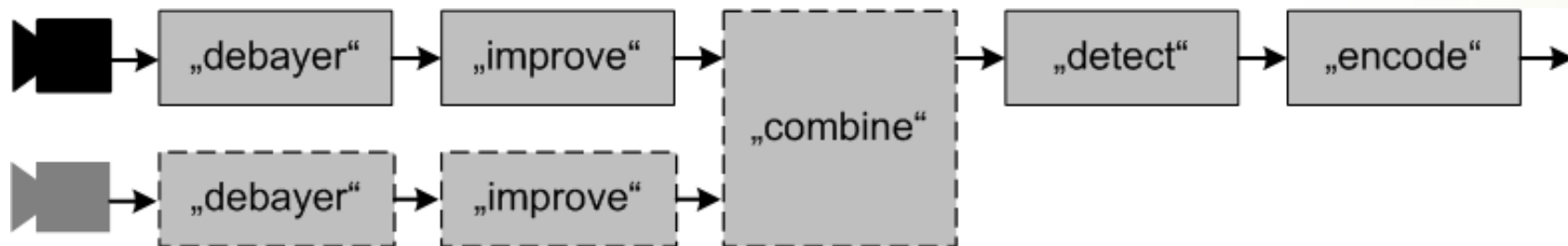


# Heterogeneous Cores for Image Sensor Processing



# ISP Algorithms

# Image Sensor Processing – Meta Pipeline



- Lens Shade Correction
- Defect Pixel Correction
- White Balance
- Debayering
- Chromatic Aberr. Corr.
- Tonemapping, Gamma
- Color Space Conversion

- Denoising
- Deshaking
- Derotation,
- Deshearing
- Deflickering

- Exposure Fusion
- Panorama View
- Image Warping
- Disparity Estimation

- Object Detection
- Object Tracking

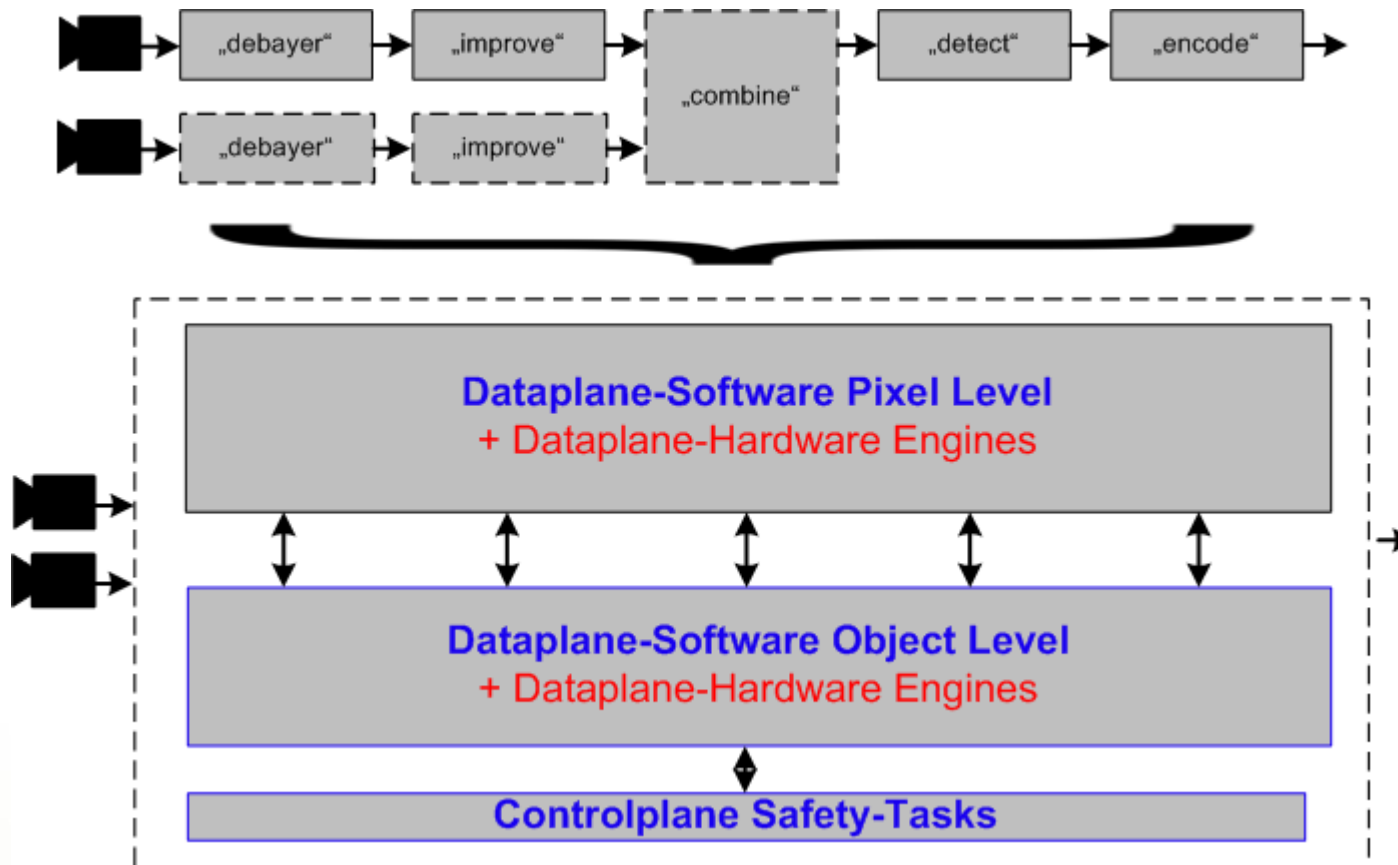
- JPEG
- H.264

## Underlying „base functions“

- 1) **ISP:** Filtering, Scaling, CSC, Histogramm&Statistics, Integral/Pyramid Images, Warping
- 2) **Motion Detection:** PPBM, PPC
- 3) **Feature Detection:** CNN, Viola-Jones, HOG, Harris Corner, SIFT, SURF
- 4) **Coding:** JPEG, H.264

## Planes and Task Types

- Data plane algorithms can be mapped on two different levels with two specific **data type and data parallelism** requirements



Requirements:

- 8-16bit
- 2D Array, long vectors
- 16-32bit
- Short Vec.
- (Security)

## *Typical Image Sensor Processing Workload*

- Small Effort Functions: ~10 Operations per Pixel
  - e.g. Gamma Corr., LSC, White Balance Gain, CSC, Cropping
- Medium Effort Functions: ~100 Operations per Pixel
  - e.g.: Debayering, CAC, small Gauss and Median Filter, Defect Pixel Correction
- High Effort Functions: ~1000 Operations per Pixel
  - e.g.: Med. Bilateral Filtering, Motion Estimation, 3DNR, Encoding /Decoding
- “Typical” ISP Pipeline: ~4k Operations per Pixel
- Lets assume 4 sensors @1080p30: 240 Mega Pixels per second  
**=> 1000 Giga Operations per second are required**

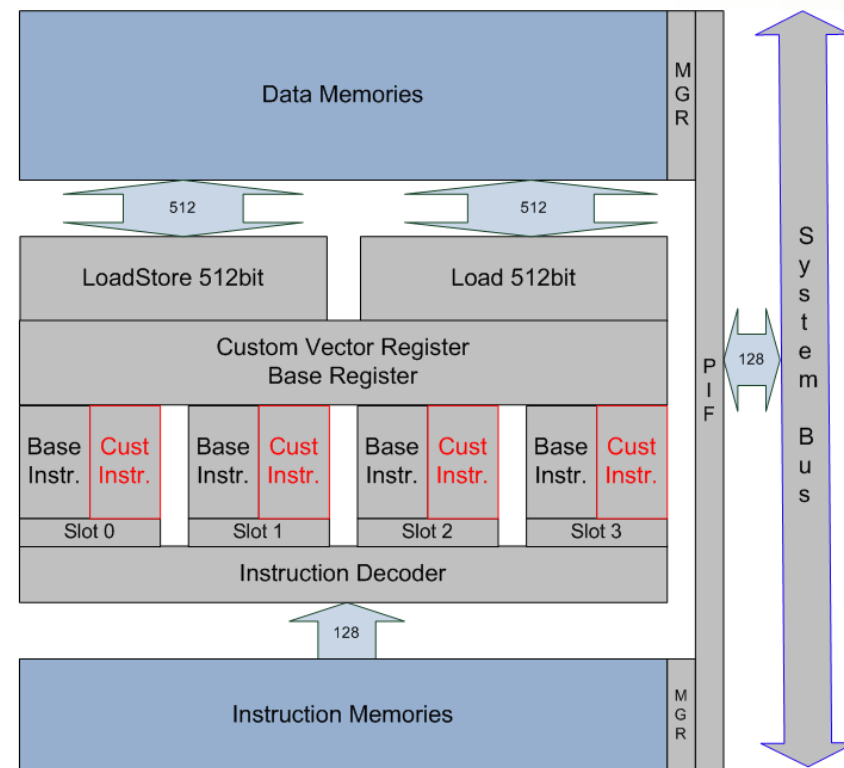
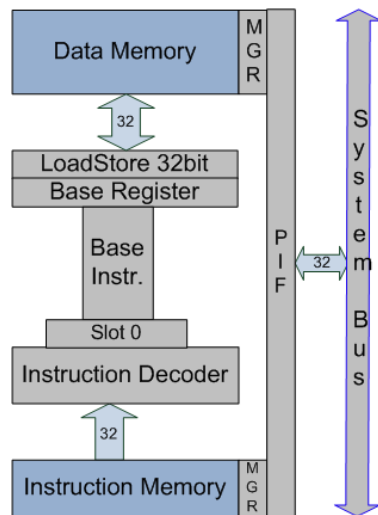
**Typical workload is beyond pure SW based embedded computing**



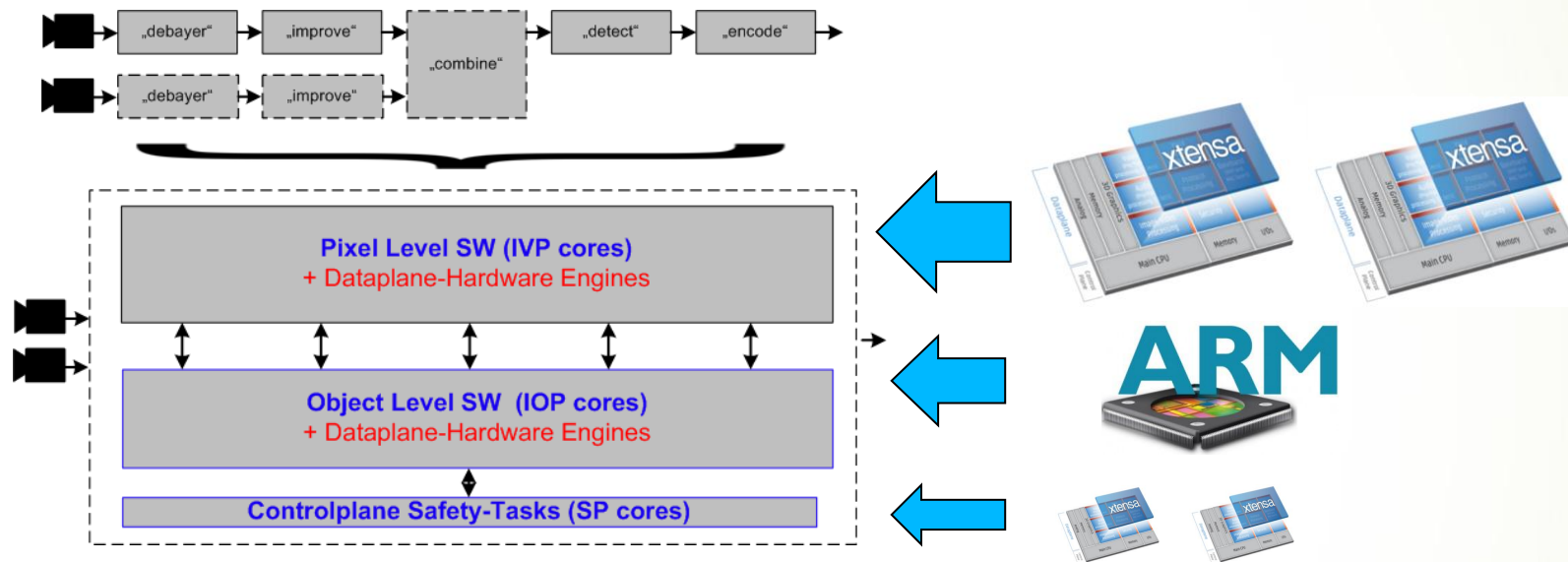
# *Architecture Proposal*

# Tensilica Core Customization – Explanation by 2 Corner Cases

- **Small Core (e.g. mini108)**
  - ~1 data plane operation per core cycle
  - 32bits L/S per core cycle
  - Base instructions
- **Big Core (e.g. IVP / Vision P5)**
  - ~100 pixel operations per core cycle
  - 1024bits L/S per core cycle
  - **Custom instructions**



# Codesign Approach



- Divide the **dataplane SW** into function on “Vectorizable Pixel Level” and “Object Level”
  - Use customized/optimized cores for the pixel level and for the object level
  - Multiple cores per class operate in parallel on pipeline stages and image segments
- Use **HW engines** for base computations which do not change (e.g. filter, transformations, compressions standards)
  - Use the dataplane SW flexibility to “glue” the HW results together

## Optimized Cores for Pixel Level and Object Level

- **Customized Core for Pixel Level**

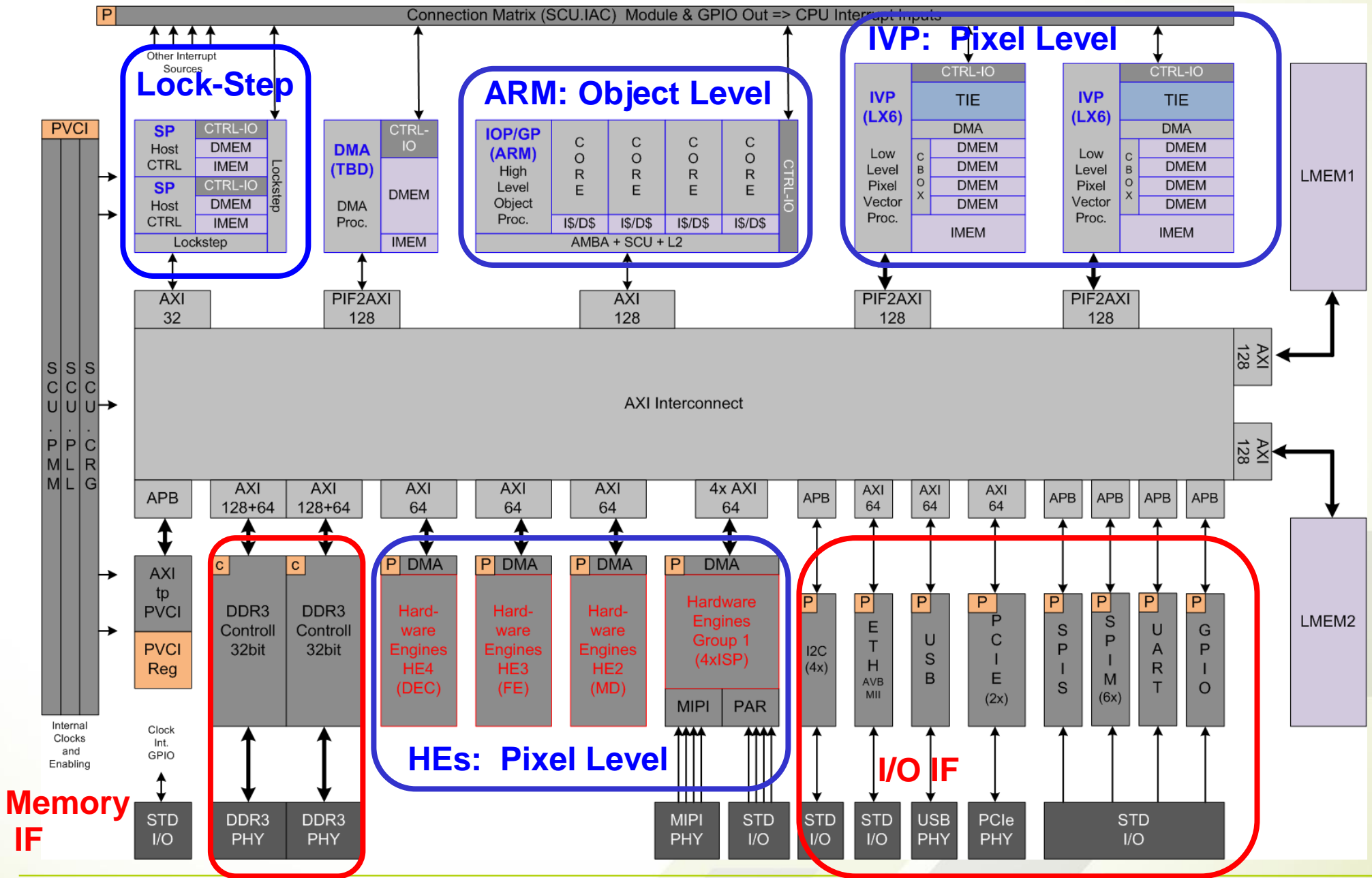
- **Tensilica/Cadence Vision P5:** Imaging Video Processor
- Predefined customization available (“Tensilica IVP”)
- 4 issue VLIW 32way SIMD custom instruction set
- App. 100 pixel level operations per clock
- Programmable by C-Code with Intrinsics



- **Pre-Optimized Core for the Object Level:**

- **ARM Cortex A17 Quad Core**
- Automotive Standard Core for Image Analysis
- Out of the box well suited for multi task 32bit object processing
  - Quad core, FPU support, short vectors by NEON
  - App. 10 object level operations per clock
- ADAS software libraries available





Memory IF

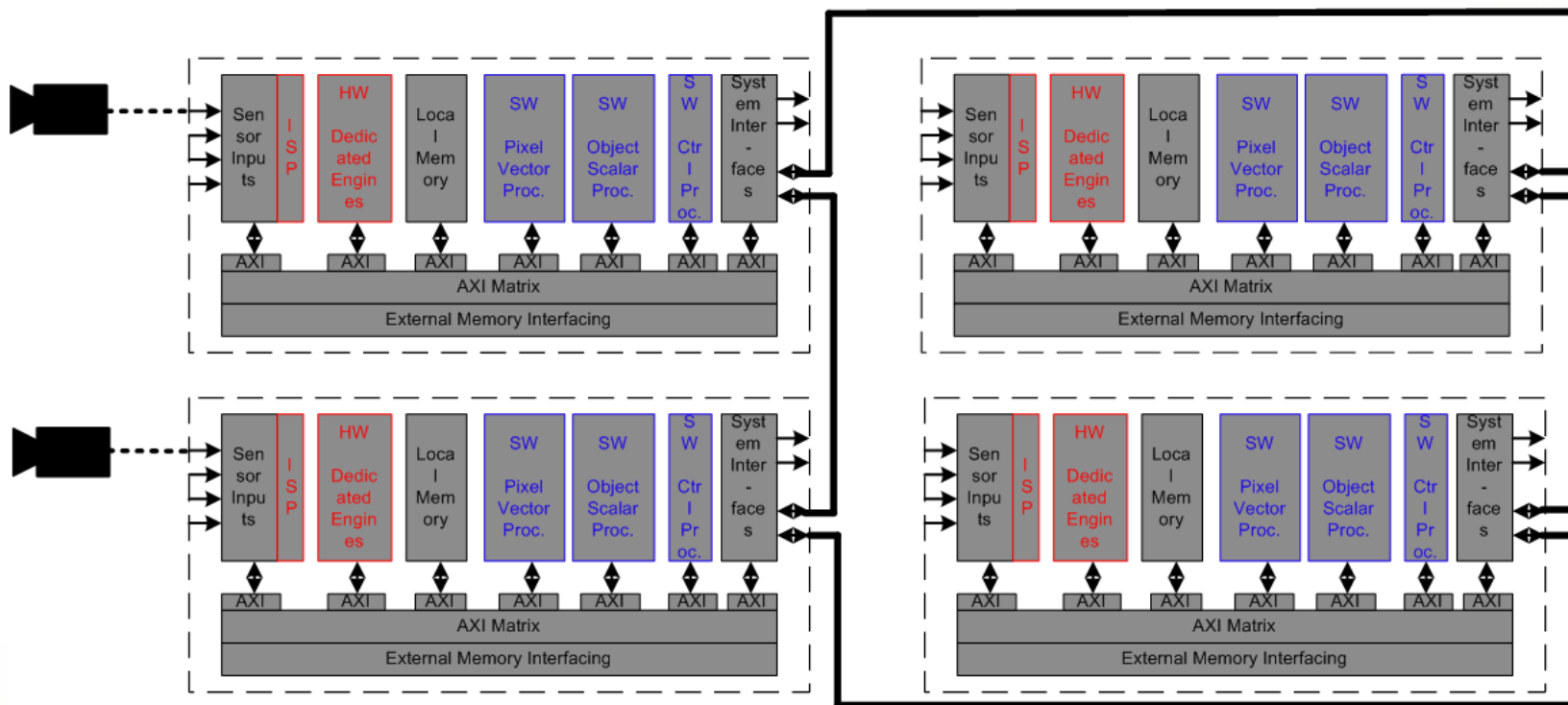
# Effort versus Performance Matrix (22nm, FDSOI)

		Area (total)	Area (PHY)	Area (Logic)	Area (Mem)	Gates	Memory	Clock	Techno-logy	Perform-ance	Power (total)	Power (PHY)	Power (Logic)	Power (Mem)
<b>Area = 38.4 mm<sup>2</sup></b>		<b>38.4</b>								<b>2.8</b>	<b>4</b>			
<b>Power = 4 Watt</b>														
Instances	#	[mm <sup>2</sup> ]	[mm <sup>2</sup> ]	[mm <sup>2</sup> ]	[kGates]	[KBytes]	[GHz]			[TOPS]	[W]	[W]	[W]	[W]
<b>CPU Cores</b>														
IVP_EP (100 op/cycle)	1	4.8	[n.a.]	0.5	4.3	1000	2172	1	LVT	100	0.55	[n.a.]	0.31	0.24
IVP_EP (100 op/cycle)	1	1.8	[n.a.]	0.5	1.3	1000	640	1	LVT	100	0.39	[n.a.]	0.31	0.07
IOP ARM A17 (10 op/cycle)	1	3.0	[n.a.]	<b>2.0</b>	1.0	[n.a.]	512	1	LVT	10	0.30	[n.a.]	<b>0.20</b>	<b>0.10</b>
SP (2xLX6) (2 op/cycle)	2	0.6	[n.a.]	0.1	0.3	100	128	0.5	RVT	2	0.04	[n.a.]	0.01	0.01
AXI Interconnect	1	0.5	[n.a.]	0.5	0.0	1000	0	0.5	RVT	[n.a.]	0.12	[n.a.]	0.12	-
<b>HW Processing</b>														
Engines 1 (1k op/cycle)	4	6.4	[n.a.]	0.8	0.9	1500	430	0.15	RVT	600	0.29	[n.a.]	0.06	0.01
Engines 2 (1k op/cycle)	1	1.3	[n.a.]	0.3	1.0	500	512	0.5	RVT	500	0.09	[n.a.]	0.06	0.03
Engines 3 (0.5k op/cycle)	1	0.9	[n.a.]	0.5	0.4	1000	192	0.5	RVT	500	0.14	[n.a.]	0.12	0.01
Engines 4 (0.5k op/cycle)	4	0.3	[n.a.]	0.1	0.0	100	9	0.5	RVT	1000	0.05	[n.a.]	0.01	0.00
<b>System Memory</b>														
DMA	1	0.2	[n.a.]	0.1	0.1	200	48	0.5	RVT	[n.a.]	0.03	[n.a.]	0.02	0.00
Local Memory (L3)	2	1.0	[n.a.]	0.0	0.5	10	256	0.5	RVT	[n.a.]	0.03	[n.a.]	0.00	0.02
DDR	2	5.3	<b>2.4</b>	0.1	0.1	200	64	0.5	RVT	[n.a.]	0.66	<b>0.3</b>	0.02	0.00
<b>Sensor Interface</b>														
MIPI-RX	4	2.0	<b>0.5</b>	0.0	0.0	0	0	0.5	RVT	[n.a.]	0.08	<b>0.02</b>	0.00	-
<b>System Interfaces</b>														
PCIe	2	3.3	<b>1.5</b>	0.1	0.1	160	32	0.5	RVT	[n.a.]	0.54	<b>0.25</b>	0.02	0.00
GBE	1	0.1	ext	0.1	0.0	200	16	0.5	RVT	[n.a.]	0.03	ext	0.02	0.00
USB3	1	1.5	<b>1.2</b>	0.1	0.3	160	128	0.5	RVT	[n.a.]	0.20	<b>0.17</b>	0.02	0.01
MIPI-TX (Display)	1	1.2	<b>1.1</b>	0.0	0.0	25	8	0.5	RVT	[n.a.]	0.04	<b>0.04</b>	0.00	0.00
SPI-M	6	0.2	[n.a.]	0.0	0.0	25	8	0.5	RVT	[n.a.]	0.02	[n.a.]	0.00	0.00
others	1	0.0	[n.a.]	0.0	0.0	25	8	0.5	RVT	[n.a.]	0.00	[n.a.]	0.00	0.00
<b>System</b>														
System controller / toplevel	1	0.1	[n.a.]	0.1	0.0	100	0	0.5	RVT	[n.a.]	0.01	[n.a.]	0.01	-
PLL	4	0.2	<b>0.04</b>	0.0	0.0	0	0	1	(n.a)	[n.a.]	0.02	<b>0.005</b>	0.00	-
Area IOs	##	2.3	[n.a.]	<b>0.007</b>	0.0	(n.a)	0	0	(n.a)	[n.a.]	0.01	[n.a.]	0.00	-
Voltage Regulators	3	1.5	<b>0.5</b>	0.0	0.0	0	0	0	(n.a)	[n.a.]	0.30	<b>0.1</b>	0.00	-

- Average area figures @ 22nm : ~2 MGates/mm<sup>2</sup> , ~0.5 MByte/mm<sup>2</sup> (large SP-SRAMs)
- Average power figures @1GHz: ~500 mW for 1mm<sup>2</sup> Logic ~100 mW for 1MByte

# System Scalability

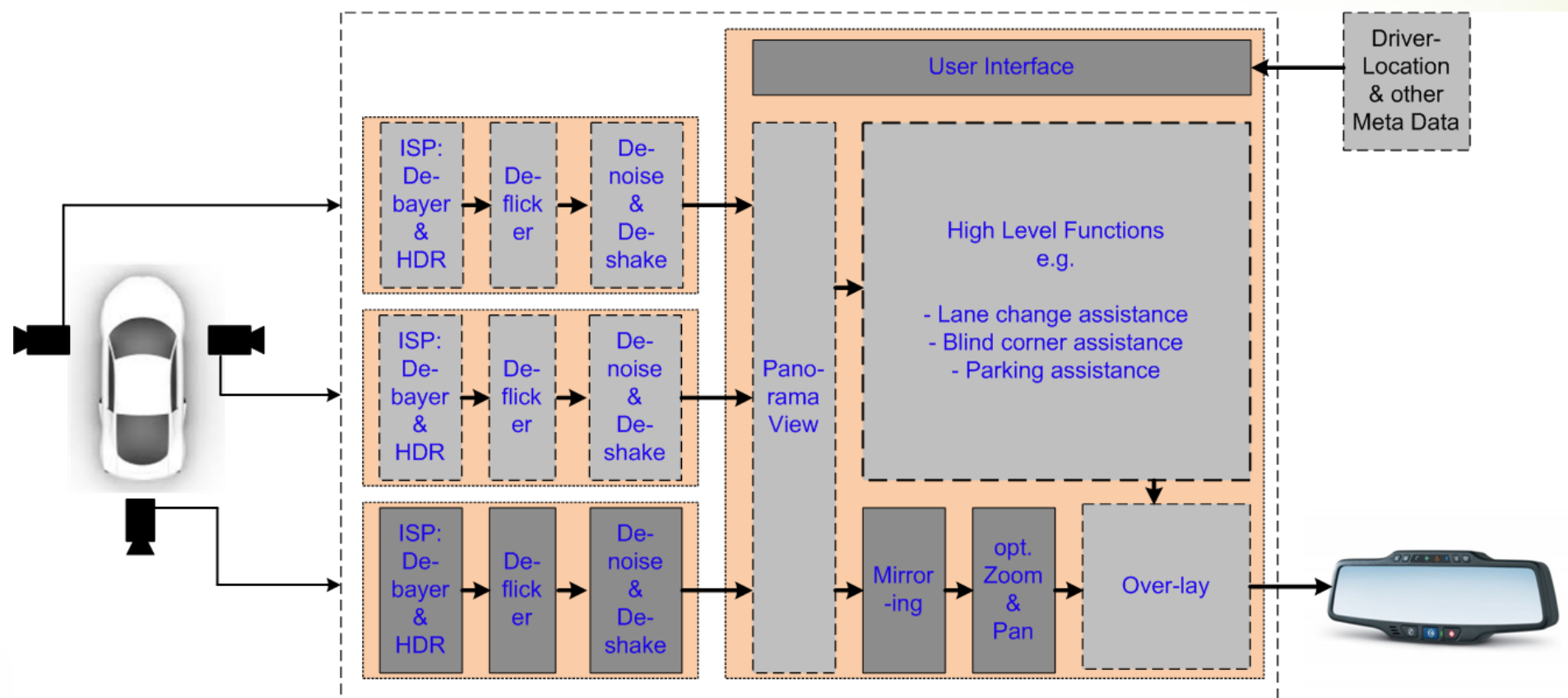
- Chip to chip interconnect by dual PCIe ports e.g. for ring interconnect



# Application Examples

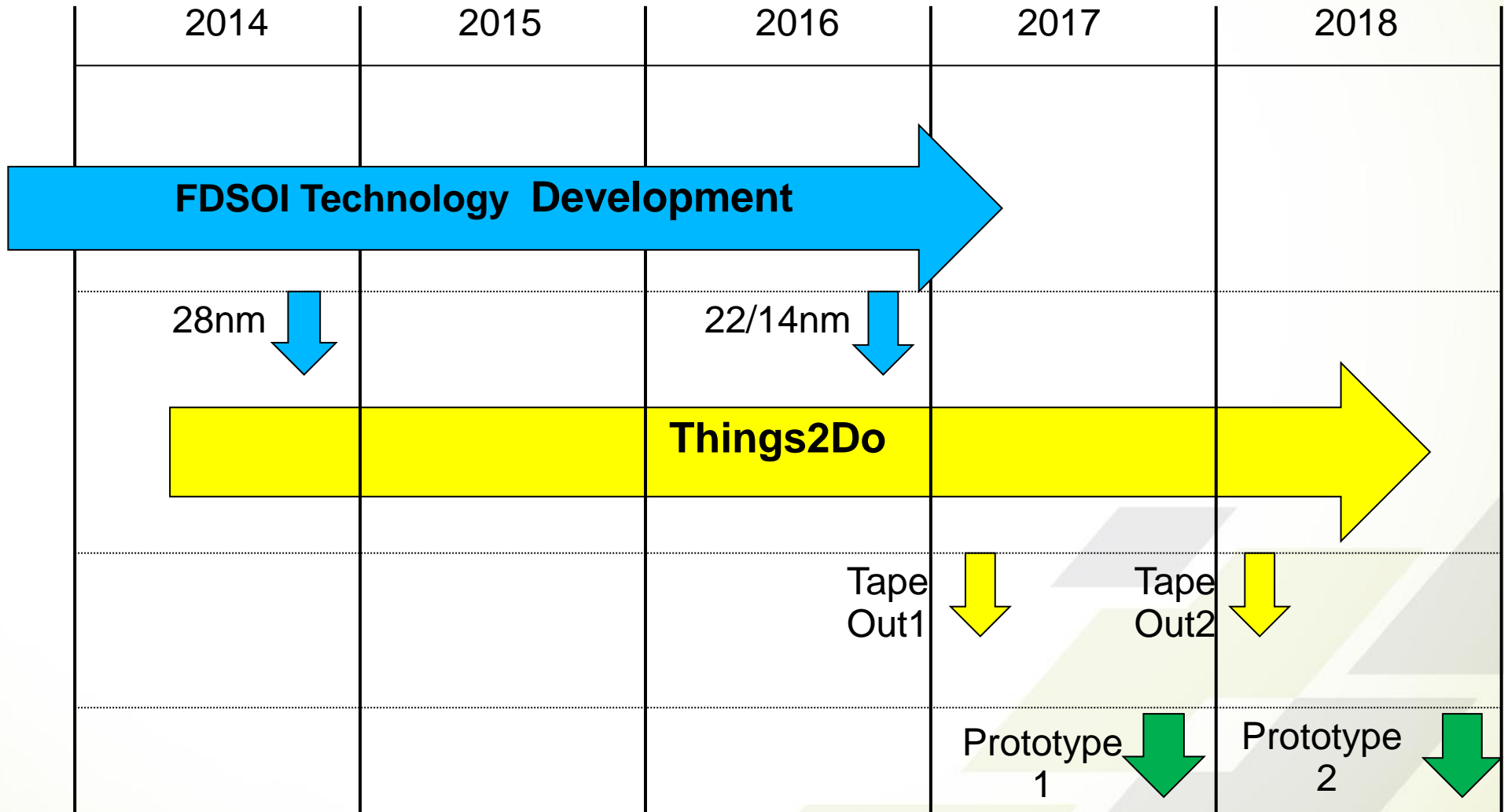


# ADAS System Study "Smart Rearview Mirror"



- System partitioning depending on customer requirements
  - Example: <http://www.bmwblog.com/2016/01/05/bmw-i8-shows-mirrorless-camera-technology/>

# Things2Do Timeline



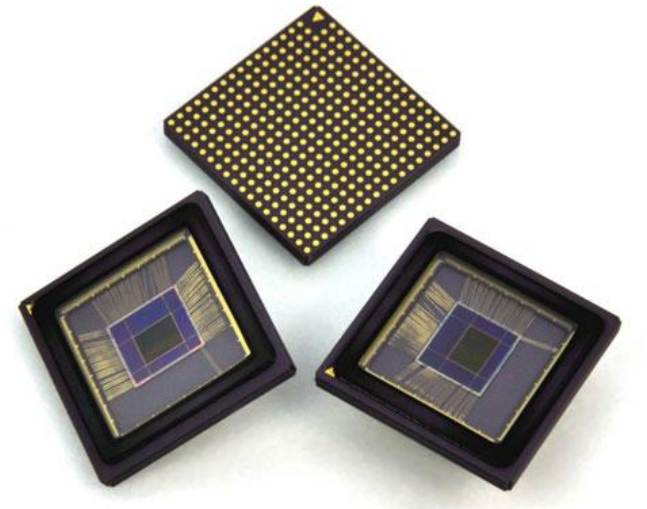
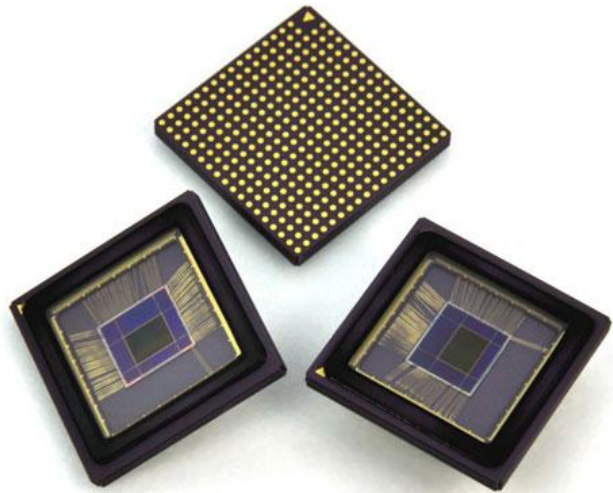
## Summary

- Introduction to the Things2Do project and DCTs contribution
- Introduction to Image Sensor Processing
  - Image Processing, Image Analysis, Computer Vision and Computer Graphics  
=> Requirements for heterogeneous computing
- ISP Algorithms
  - Meta Pipeline, Base Functions, Quantitative Analysis  
=> Requirements for base functions in HW
- ISP Architecture
  - Suggestion for a “Trinity” on the data plane:  
=> SW for Object Level, SW for Pixel Level and HW Engines for “base functions”
- ISP Applications
  - Examples with Application-to-Architecture Mappings

*Thank You!*



# Thank You!



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